IN THE CLAIMS:

Please amend the claims as follows:

1 – 12. (Canceled)

13. (Previously presented) A method of manufacturing a module component comprising:

forming a plurality of penetration holes in a substrate made of resin, so as to form a matrix of N aligned rows and M aligned columns of said penetration holes, each of said penetration holes being aligned in both a row and a column of said matrix, and each row and each column of said matrix comprising at least three penetration holes;

inserting a chip component into one of said plurality of penetration holes, the chip component having an almost same height as a depth of the one of said plurality of penetration holes;

forming a circuit wiring for coupling the chip component on said substrate; and

heating, compressing, and adhering an auxiliary substrate on at least one of both sides of the substrate,

wherein N is equal to or greater than 3, and M is equal to or greater than 3.

14 – 26. (Canceled)

27. (Original) A manufacturing method of a module component comprising:

an inserting step of inserting a chip component in a molding die;

a primary molding step of filling the molding die with resin with an end electrode of the chip component exposed;

a peeling step of peeling the molding die at a side of inserting the chip component;

a secondary molding step of filling the molding die with resin with an end electrode of the chip component; and

a forming step of forming a circuit wiring on one side or both sides of a molded element molded with resin, wherein the chip component is disposed according to a specified rule, and the chip component are molded with the resin to compose a desired circuit.

28. (Original) A manufacturing method according to claim 27, wherein the chip component is disposed in a specified position according to a matrix, and the chip component of a specific value is molded with the resin to compose a desired circuit.

29. (Original) A manufacturing method according to claim 28, wherein a dummy component having a same size as the chip component is inserted at a position where the chip component is not inserted according to the matrix.

30. (Original) A manufacturing method of a module component comprising:

an inserting step of inserting a chip component in a molding die, the chip component being disposed according to a specified rule;

a primary molding step of filling with resin with an end electrode of the chip component exposed;

a peeling step of peeling the molding die at a side of inserting the chip component;

a secondary molding step of filling with resin with an end electrode of the chip component exposed; and

a step of mounting an IC chip on one side of a molded element molded with resin and coupling an other side to a substrate, wherein a electrode terminal of the IC chip is directly coupled with a circuit wiring on the substrate through the chip component.

31. (New) A manufacturing method of claim 28, wherein the matrix has N aligned rows and M aligned columns, N being equal to or greater than 3, and M being equal to or greater than 3.